













Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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06 155 FR4 35 L10.35 P18_06 s1

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

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Layers	in μ	Material	Build-Up	Assembly				
Layer-1	35 μ	Copper		} A1				
	60 μ	Prepreg			(60 μ PrePreg-Type: 1080)			
Layer-2	60 μ	Prepreg			} B			
	35 μ	Copper						
Layer-3	100 μ	L-FR4					} A2	
	35 μ	Copper						
Layer-4	180 μ	Prepreg						} B
	180 μ	Prepreg				(180 μ PrePreg-Type: 7628)		
	180 μ	Prepreg						
	180 μ	Prepreg						
	180 μ	Prepreg						
180 μ	Prepreg							
Layer-5	35 μ	Copper		} A2				
	100 μ	L-FR4						
Layer-99	35 μ	Copper				} B		
	60 μ	Prepreg						
Layer-99	60 μ	Prepreg					} B	
	35 μ	Copper						

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